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File: JPAB

Aug 28, 1991

PUB-NO: JP403197137A

DOCUMENT-IDENTIFIER: JP 03197137 A

TITLE: HEAT SHRINKABLE LAMINATED FILM AND MANUFACTURE THEREOF

PUBN-DATE: August 28, 1991

## INVENTOR-INFORMATION:

NAME

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APPL-DATE: December 27, 1989

US-CL-CURRENT: 428/474.4; 428/475.2

INT-CL (IPC): B32B 27/28; B32B 27/32

## ABSTRACT:

PURPOSE: To elevate the strength of a laminate and the strength of a heat seal, and prevent the occurrence of bag breakage or interlayer separation by making a heat seal layer comprise an inner layer being composed of low density polyethylene (LDPE), ethylene - vinyl acetate copolymer (EVOH), or ionomer, and an outer layer being composed of straight chain low density polyethylene (L-LDPE) or EVOH, and also making the outer layer constitute an outer surface.

CONSTITUTION: A heat shrinkable laminated film is made such that a heat seal layer is laminated on a heat shrinkable polyamide film via an anchor coat layer. The heat seal layer comprises an inner layer being composed of LDPE, EVOH or ionomer, and an outer layer being composed of L - LDPE or EVOH, and the outer layer is laminated thereon to constitute an outer surface. Since the heat shrinkable laminated film has an extraordinarily large laminate strength, there is no possibility of delamination, and as the heat seal strength during bag manufacturing and sealing period is very large, it does not break at the sealed portion and can be used as the bag of a bag manufacturing method by mitered adhesion.

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<u>DB Name</u>	<u>Query</u>	<u>Hit C unt</u>	<u>Set Name</u>
USPT,JPAB,EPAB,DWPI,TDBD	L7 and (ethylene near vinyl acetate) and (\$4ethylene near (low density or high density)) and heat seal\$.ab.	107	<u>L9</u>
USPT,JPAB,EPAB,DWPI,TDBD	L7 and (ethylene near vinyl acetate) and (\$4ethylene near (low density or high density)) and heat seal\$	451	<u>L8</u>
USPT,JPAB,EPAB,DWPI,TDBD	(428/323)!.CCLS. or 428/328.ccls. or 428/331.ccls. or 428/411.1.ccls. or 428/412.ccls. or 428/457.ccls. or 428/461.ccls. or 428/474.4.ccls. or 428/475.8.ccls. or 428/476.3.ccls. or 428/480.ccls. or 428/483.ccls. or 428/500.ccls. or 428/515.ccls. or 428/532.ccls. or 428/537.1.ccls. or 428/537.5.ccls. or 428/923.ccls. or 428/926.ccls. or 442/.286.ccls. or 442/268.ccls. or 442/277.ccls. or 442/286.ccls. or 442/288.ccls. or 442/290.ccls. or 442/394.ccls. or 442/396.ccls. or 442/398.ccls.	25486	<u>L7</u>
USPT,JPAB,EPAB,DWPI,TDBD	L4 and metallocene	45	<u>L6</u>
USPT,JPAB,EPAB,DWPI,TDBD	L3 and (heat seal\$.ab.)	96	<u>L5</u>
USPT,JPAB,EPAB,DWPI,TDBD	L3 and heat seal\$	489	<u>L4</u>
USPT,JPAB,EPAB,DWPI,TDBD	(ethylene near vinyl acetate) and (\$4ethylene near (low density or high density)) and (428/\$)!.CCLS. and polyamide	1042	<u>L3</u>
USPT,JPAB,EPAB,DWPI,TDBD	(ethylene near vinyl acetate) and (\$4ethylene near (low density or high density)) and (428/\$)!.CCLS.	2064	<u>L2</u>
USPT,JPAB,EPAB,DWPI,TDBD	(ethylene near vinyl acetate) and (\$4ethylene) and (428/\$)!.CCLS.	5603	<u>L1</u>